



## Material Content Data Sheet



Sales Product Name	BSO033N03MS G			Issued		11. December 2019		
MA#	MA000466280							
Package	PG-DSO-8-39			Weight*		84.11 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.944	3.50	3.50	35002	35002
leadframe	inorganic material	phosphorus	7723-14-0	0.010	0.01		122	
	non noble metal	zinc	7440-66-6	0.041	0.05		487	
	non noble metal	iron	7439-89-6	0.820	0.97		9744	
	non noble metal	copper	7440-50-8	33.276	39.56	40.59	395633	405986
wire	non noble metal	copper	7440-50-8	0.378	0.45	0.45	4489	4489
encapsulation	organic material	carbon black	1333-86-4	0.225	0.27		2670	
	plastics	epoxy resin	-	6.961	8.28		82764	
	inorganic material	silicondioxide	60676-86-0	37.725	44.85	53.40	448528	533962
leadfinish	non noble metal	tin	7440-31-5	0.814	0.97	0.97	9676	9676
plating	noble metal	silver	7440-22-4	0.073	0.09	0.09	863	863
glue	plastics	epoxy resin	-	0.126	0.15		1503	
	noble metal	silver	7440-22-4	0.717	0.85	1.00	8519	10022
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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